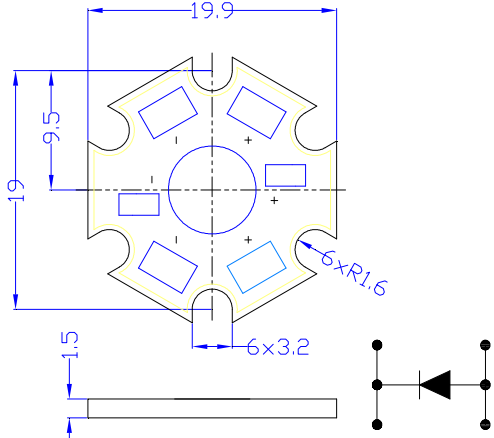

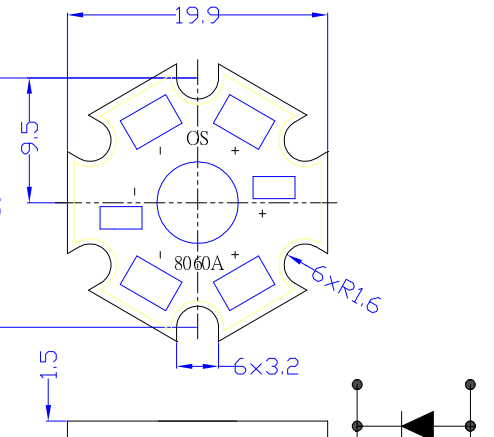



Heat Sink for Xeon Series					
Item	Part Number	Description	Dimension	Photo	Application
1W	OSMCPCB8060B	<ul style="list-style-type: none"> <li>Aluminum metal-base copper-clad laminate PCB</li> <li>Design for Xeon 1 Power Series LED</li> <li>Base metal is 1.5mm Aluminum</li> <li>With NTCD Thermally Conductive Dielectric</li> <li>Copper Circuit Foil is 35 <math>\mu</math> m(1oz)</li> <li>Surface Finish is Black Solder Mask, Pb-free HASL solder pads (RoHS compliant)</li> </ul>	 <p>Unit:mm Tolerance:±0.30mm</p>		Used for Xeon 1 Power Series, eg: OSW4XME1C1E
3W	OSMCPCB8060A	<ul style="list-style-type: none"> <li>Aluminum metal-base copper-clad laminate PCB</li> <li>Design for Xeon 3 Power Series LED</li> <li>Base metal is 1.5mm Aluminum</li> <li>With HTCD Thermally Conductive Dielectric to suitable high power LED</li> <li>Copper Circuit Foil is 35 <math>\mu</math> m(1oz)</li> <li>Surface Finish is White Solder Mask, Pb-free HASL solder pads (RoHS compliant)</li> </ul>	 <p>Unit:mm Tolerance:±0.30mm</p>		Used for Xeon 3 Power Series, eg: OSW4XME1C1E

## Appendix

### Data and information for MCPCB

<u>Items</u>	<u>Unit</u>	<u>Reference</u>
<b>Thermal Conductivity</b>	W/mK	0.8W/mK
<b>Dielectric thickness</b>	$\mu$ m	100
<b>Breakdown voltage</b>	kV(DC)	> 3kV
<b>Insulation resistance</b>	$\Omega$	$10^5$
<b>Maximum Working Temperature</b>	$^{\circ}$ C	130
<b>Peel Strength</b>	N/mm	> 1.4
<b>Blistering after heat shock within 1 minutes</b>	$^{\circ}$ C	<260
<b>Copper thickness</b>	$\mu$ m	35
<b>Base metal plate</b>	-	Aluminum
<b>Base metal thickness</b>	mm	1.5